

IEC-IEEE development of dual logo standards

Kjell Spång
KS miltek

Joint development programs in pipe-line

- Methods for condition monitoring
- Joint revision of IEC 60780 and IEEE 323
- Control Rooms – Computer Based Procedures

The Joint IEC-IEEE development of standards on methods for condition monitoring is a pilot application of the new agreement

Project 62582

Structure

- One general part and one separate part for each condition monitoring method.
- Each part will be issued as a separate standard but with the same basic identification number

IEC/IEEE 62582-n

**Nuclear power plants – Instrumentation and control
important to safety – Electrical equipment condition
monitoring methods**

Part 1: General

Part 2: Indenter modulus

Part 3: Elongation at break

Part 4: Oxidation induction techniques

Part 5: Oxidation time domain reflectrometry

Participation from IEEE

- Initiated by IEC
- Project leader: Kjell Spång; Co-project leader: Jim Gleason
- Other participants in the project team who are members in IEEE
 - Tom Koshy, attended both meetings (together with Sheila Rey at the first meeting, together with George Wilson at the second meeting)
 - Marco van Uffelen, attended both meetings
 - Charles Hills, attended last meeting
 - Marek Tengler, through correspondence
 - Steve Casadevall, expressed interest; on mailing list
 - Jan Pirrong, invited; on mailing list
 - John White, Invited; on mailing list

Scott Malcolm is an official member of the Project Team from Canada (IEC)

Gary Toman has contributed in the development of the part 2 Indenter modulus

Schedule

- Started in connection with the SC45AWG10 meeting in London in Spring 2008, based on adoption by SC45A of a Swedish NWIP.
- September 25 and 26, 2008: First meeting of the Project team in Forsmark, Sweden.
- January 12-13, 2009 : Second meeting of the Project Team in Brussels.
- May 7-8: Third meeting of the Project team, at which the final formulation of the drafts will be decided upon.
- End of May 2009: The project leader submits the first drafts to IEC and IEEE (Part 1 General, Part 2 Indenter, Part 3 OIT/OITP)